



SHENZHEN TUOFENG SEMICONDUCTOR TECHNOLOGY CO.,LTD

SOP-8 Plastic-Encapsulate MOSFETS

4409

P-Channel Enhancement Mode Power MOSFET

Description

The 4409 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V.

General Features

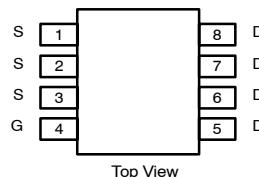
- $V_{DS} = -30V$
- $R_{DS(ON)} < 15m\Omega @ V_{GS}=-4.5V \quad I_D = -12.0A$
- $R_{DS(ON)} < 12m\Omega @ V_{GS}=-10V \quad I_D = -15.0A$

- High power and current handing capability
- Lead free product is acquired
- Surface mount package

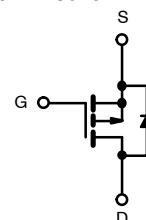
Application

- Battery Switch
- Load switch
- Power management

SOP-8



Equivalent Circuit



MARKING



Y : year code W : week code

Absolute Maximum Ratings ($T_A=25^\circ C$, unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current @ $T_A=25^\circ C$	-15	A
I_{DM}	Drain Current (Pulsed) ^a	-60	A
I_{AR}	Avalanche Current	30	A
E_{AR}	Repetitive Avalanche Energy L=0.3mH	135	mJ
P_D	Total Power Dissipation @ $T_A=25^\circ C$	3.1	W
	Total Power Dissipation @ $T_A=75^\circ C$	2.1	
I_S	Maximum Diode Forward Current	-2.1	A
T_j, T_{stg}	Operating Junction and Storage Temperature Range	-55 to +150	°C
$R_{\theta JA}$	Thermal Resistance Junction to Ambient (PCB mounted) ^b	40	°C/W

a: Repetitive Rating: Pulse width limited by the maximum junction temperature.

b: 1-in² 2oz Cu PCB board



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Electrical Characteristics ($T_A=25^\circ\text{C}$, unless otherwise noted)

Symbol	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
• Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-24\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 25\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
• On Characteristics^c						
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.0	-	-3.0	V
$I_{\text{DS(on)}}$	On State Drain Current	$V_{\text{DS}}=-5\text{V}, V_{\text{GS}}=-10\text{V}$	60	-	-	A
$R_{\text{DS(on)}}$	Drain-Source On-State Resistance	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-15\text{A}$	-	9.5	12	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-12\text{A}$	-	13	15	
g_{FS}	Forward Transconductance	$V_{\text{DS}}=-10\text{V}, I_{\text{D}}=-5\text{A}$	-	26	-	S
• Dynamic Characteristics^d						
C_{iss}	Input Capacitance	$V_{\text{DS}}=-15\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	-	290	-	pF
C_{oss}	Output Capacitance		-	410	-	
C_{rss}	Reverse Transfer Capacitance		-	280	-	
R_g	Gate Resistance	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	1	2	3	Ω
• Switching Characteristics^d						
Q_g	Total Gate Charge	$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-10\text{A}, V_{\text{GS}}=-10\text{V}$	-	48	-	nC
Q_{gs}	Gate-Source Charge		-	12	-	
Q_{gd}	Gate-Drain Charge		-	14	-	
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=-15\text{V}, I_{\text{D}}=-10\text{A}, V_{\text{GS}}=-10\text{V}$ $V_{\text{GS}}=-10\text{V}, R_{\text{G}}=3\Omega$	-	15	-	nS
t_r	Turn-on Rise Time		-	11	-	
$t_{\text{d(off)}}$	Turn-off Delay Time		-	44	-	
t_f	Turn-off Fall Time		-	21	-	
t_{rr}	Reverse Recovery Time	$I_{\text{DS}}=-12\text{A}, \frac{dI}{dt}=100\text{A/uS}$	-	33	40	nS
Q_{rr}	Reverse Recovery Charge		-	23	-	nC
• Drain-Source Diode Characteristics						
V_{SD}	Drain-Source Diode Forward Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=-1\text{A}$	-	-	-1	V
I_{S}	Drain-Source Diode Forward Current		-	-	-2.1	A

Note: Pulse Test: Pulse Width $\leq 300\text{us}$, Duty Cycle $\leq 2\%$

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Typical Electrical and Thermal Characteristics

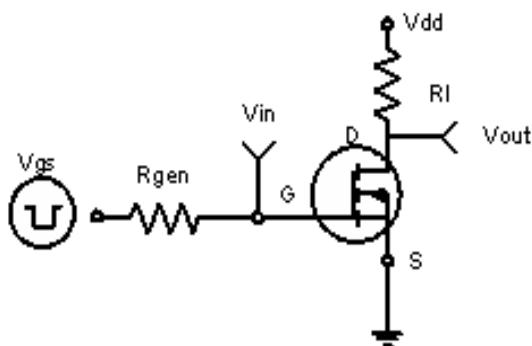


Figure 1 Switching Test Circuit

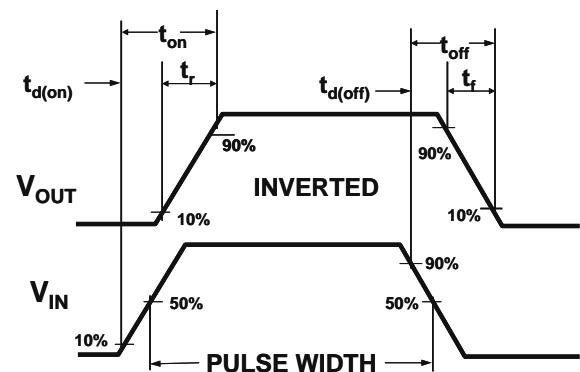


Figure 2 Switching Waveforms

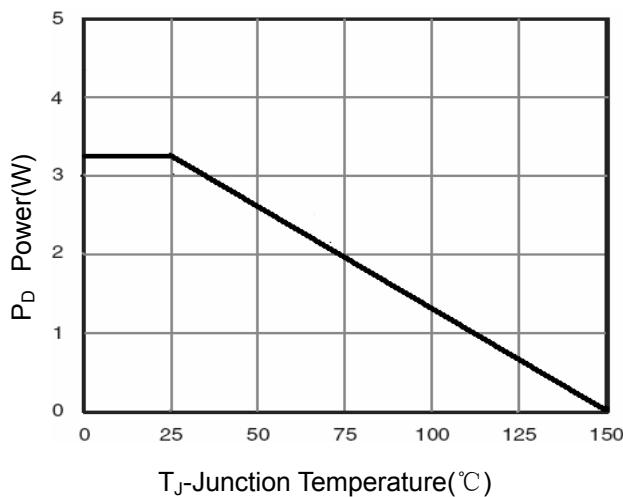


Figure 3 Power Dissipation

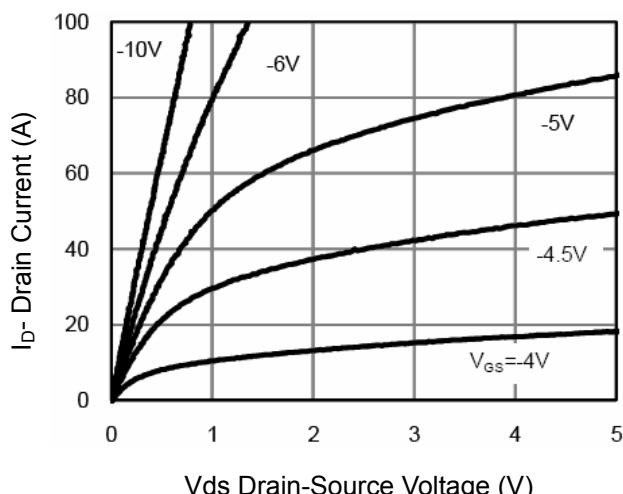


Figure 5 Output Characteristics

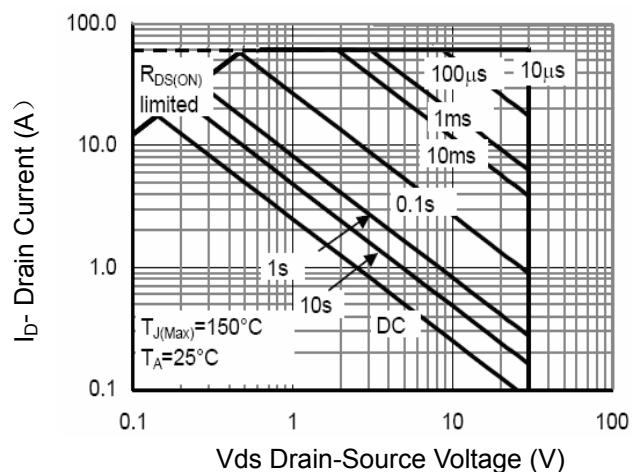


Figure 4 Safe Operation Area

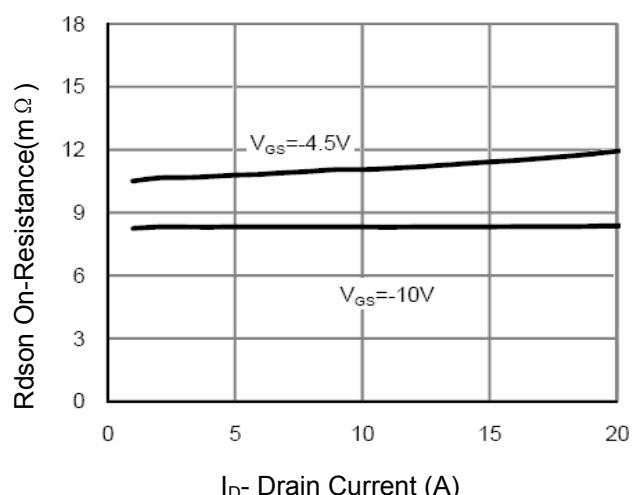


Figure 6 Drain-Source On-Resistance

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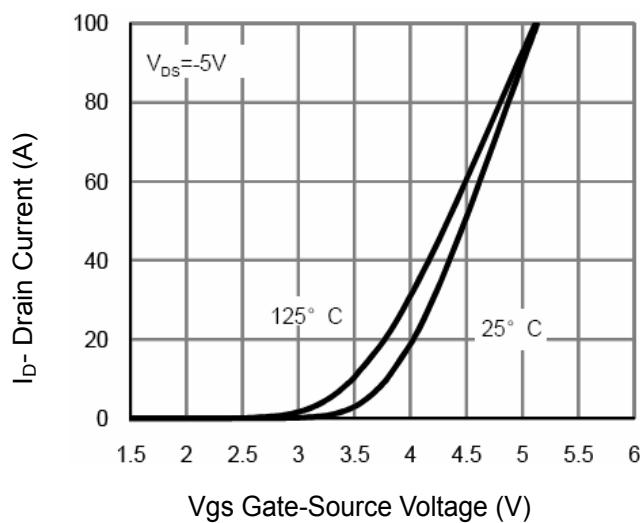


Figure 7 Transfer Characteristics

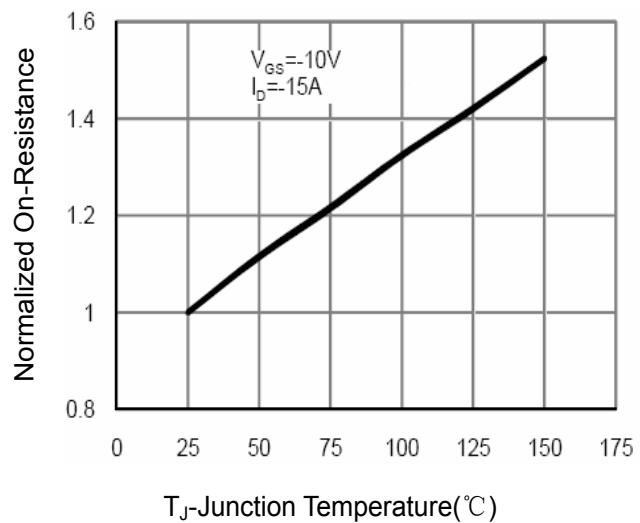


Figure 8 Drain-Source On-Resistance

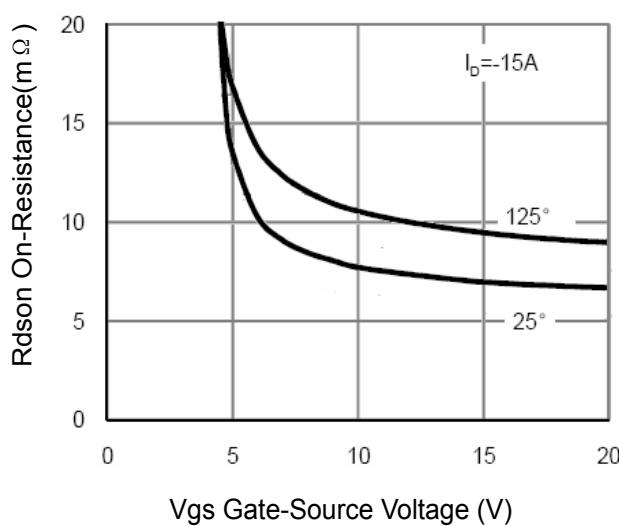


Figure 9 $R_{DS(on)}$ vs V_{GS}

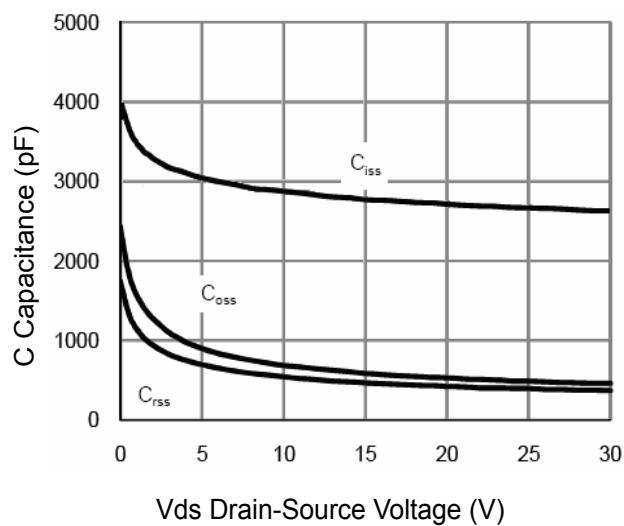


Figure 10 Capacitance vs V_{DS}

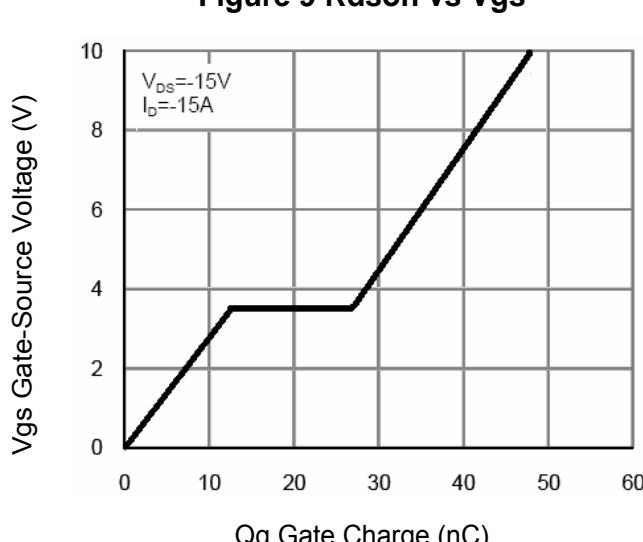


Figure 11 Gate Charge

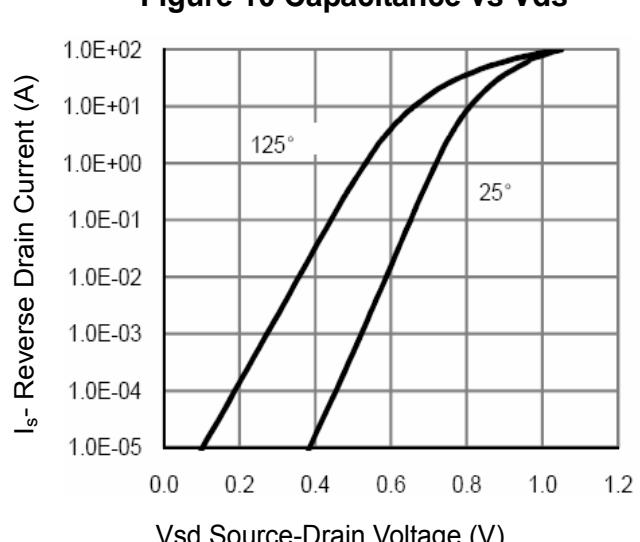


Figure 12 Source-Drain Diode Forward

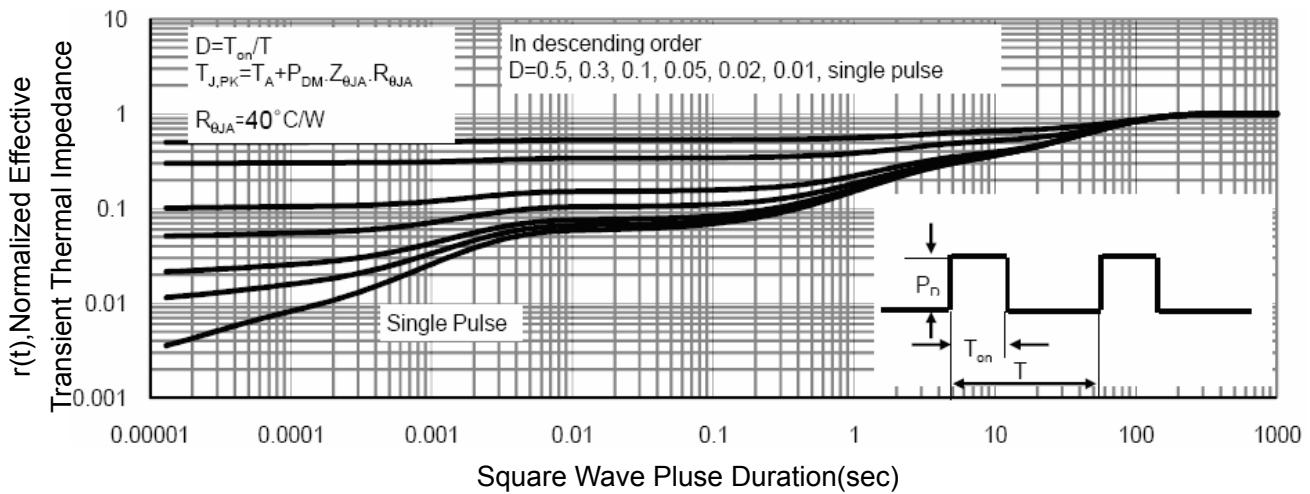
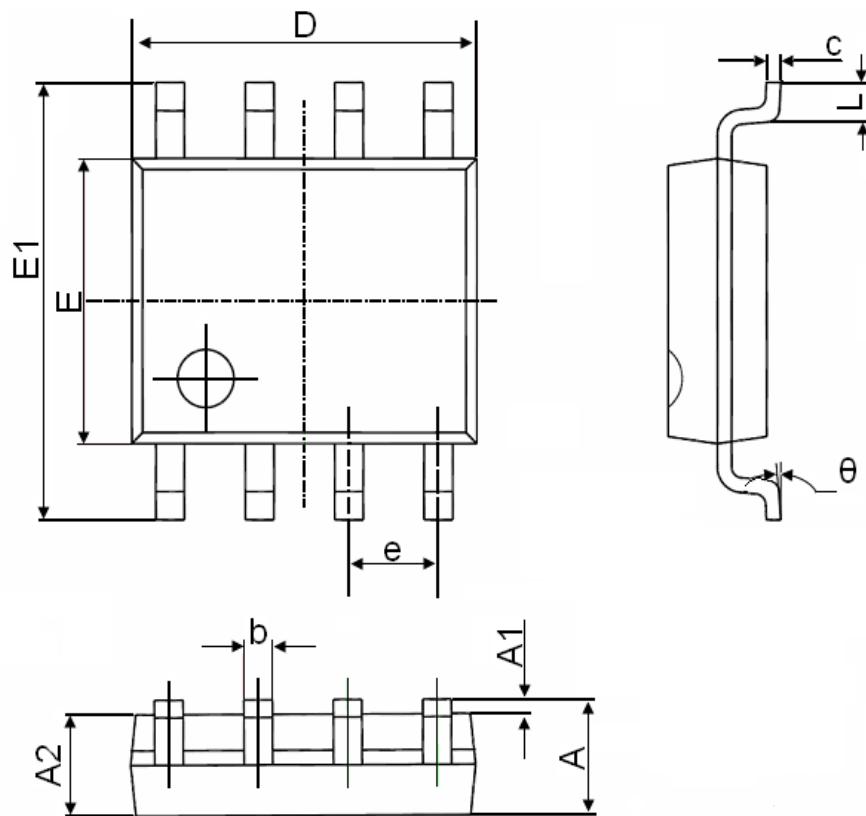


Figure 13 Normalized Maximum Transient Thermal Impedance

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SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°